PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6801841

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSIN-LI CHENG	02/24/2020
JYUN-YING LIN	02/24/2020
ALEXANDER KALNITSKY	03/06/2020
SHIH-FEN HUANG	03/06/2020
SHU-HUI SU	02/24/2020
TING-CHEN HSU	02/24/2020
TUO-HSIN CHIEN	02/24/2020
FELIX YING-KIT TSUI	02/24/2020
SHI-MIN WU	02/24/2020
YU-CHI CHANG	02/24/2020

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17370067

CORRESPONDENCE DATA

Fax Number: (216)502-0601

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 216-502-0600
Email: docketing@epiplaw.com
Correspondent Name: ESCHWEILER & POTASHNIK, LLC
Address Line 1: ROSETTA CENTER
Address Line 2: 629 EUCLID AVE., SUITE 1101
Address Line 4: CLEVELAND, OHIO 44114

ATTORNEY DOCKET NUMBER:	TSMCP1159USA
NAME OF SUBMITTER:	NICOLAS A. SMITH
SIGNATURE:	/Nicolas A. Smith/
DATE SIGNED:	07/08/2021

Total Attachments: 12

source=Assignment#page1.tif
source=Assignment#page2.tif
source=Assignment#page3.tif
source=Assignment#page4.tif
source=Assignment#page5.tif
source=Assignment#page6.tif
source=Assignment#page7.tif
source=Assignment#page8.tif
source=Assignment#page9.tif
source=Assignment#page10.tif
source=Assignment#page11.tif
source=Assignment#page12.tif

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Hsin-Li Cheng

Assignor(s):
Jyun-Ying Lin

Assignor(s):
Alexander Kalnitsky

Assignor(s):
Shih-Fen Huang

Assignor(s):
Shu-Hui Su

Assignor(s):
Ting-Chen Hsu

Assignor(s):
Tuo-Hsin Chien

Assignor(s):
Felix Ying-Kit Tsui

Assignor(s):
Shi-Min Wu

Assignor(s):
Yu-Chi Chang

Assignee:
Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled **"TRENCH CAPACITOR PROFILE TO DECREASE SUBSTRATE WARPAGE"** for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. ________________________,

filed on ________________________.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2020. 2. 24
Date

Hsin-Li Cheng
Name 1st Inventor Hsin-Li Cheng

2020.02.24
Date

Jyun-Ying Lin
Name 2nd Inventor Jyun-Ying Lin

3-6-2020
Date

Name 3rd Inventor Alexander Kalnitsky

3/6/2020
Date

Name 4th Inventor Shih-Fen Huang

2020/2/24
Date

Shu-Hui Su
Name 5th Inventor Shu-Hui Su

2020, 2-27
Date

Ting-Chen Hsu
Name 6th Inventor Ting-Chen Hsu

2/24/2020
Date

Tuo-Hsin Chien
Name 7th Inventor Tuo-Hsin Chien

2/24/2020.
Date

Felix Tsui
Name 8th Inventor Felix Ying-Kit Tsui

2020/2/24
Date

Shi-Min Wu
Name 9th Inventor Shi-Min Wu

2020/2/24
Date

Yu-Chi Chang
Name 10th Inventor Yu-Chi Chang